



February 16, 2017

Ultratech Receives Large, Repeat Multiple System Order For Leading-Edge, Fan-Out Wafer-Level Packaging Applications

Ultratech's AP300 Lithography Systems will be used for Next-generation, High-volume, Fan-out Wafer-level Packaging Applications

SAN JOSE, Calif., Feb. 16, 2017 /PRNewswire/ -- **Ultratech, Inc.** (Nasdaq: UTEK), a leading supplier of lithography, laser processing and inspection systems used to manufacture semiconductor devices and high-brightness LEDs (HBLEDs), as well as atomic layer deposition (ALD) systems, today announced that it has received a repeat, multiple-system order from a leading semiconductor manufacturer for its advanced packaging AP300 lithography systems. The AP300 systems will be utilized for high-volume, leading-edge, fan-out wafer-level packaging (FOWLP) applications used to manufacture state-of-the-art application processors. Ultratech will begin shipping the AP300 systems in the first two quarters of this year to the customer's facility in Asia.

Ultratech General Manager and Vice President of Lithography Products Rezwan Lateef stated, "Ultratech has maintained its leadership position in the advanced packaging market segment by consistently delivering superior on-wafer results, cost-of-ownership and reliability performance for high-volume manufacturing (HVM) environments. Fan-out technologies continue to be the optimal solution for the highly-demanding mobile and wireless markets by offering improved performance in a reduced form factor. The AP300 is ideally suited to address this market with HVM -proven extendibility well below 2 microns. This substantial repeat order again confirms our technology leadership and the value proposition of Ultratech's AP300 systems over full-field 1X scanners and reduction steppers. We are pleased to expand our photolithography-tool-of-record position at this valued customer. We look forward to working with them to meet their volume production and technology roadmaps."

Ultratech's AP300 Family of Lithography Steppers

The AP300 family of lithography systems is built on Ultratech's customizable Unity Platform™, delivering superior overlay, resolution and side wall profile performance and enabling highly-automated and cost-effective manufacturing. These systems are particularly well suited for copper pillar, fan-out, through-silicon via (TSV) and silicon interposer applications. In addition, the platform has numerous application-specific product features to enable next-generation packaging techniques, such as Ultratech's award winning dual-side alignment (DSA) system, utilized around the world in volume production.

Safe Harbor

This release includes forwardlooking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Forwardlooking statements can generally be identified by words such as "anticipates," "expects," "remains," "thinks," "intends," "believes," "estimates," and similar expressions and include management's current expectation of its longer term prospects for success. These forwardlooking statements are based on our current expectations, estimates, assumptions and projections about our business and industry, and the markets and customers we serve, and they are subject to numerous risks and uncertainties that may cause these forwardlooking statements to be inaccurate. Such risks and uncertainties include the timing and possible delays, deferrals and cancellations of orders by customers; quarterly revenue fluctuations; industry and sector cyclicalities, instability and unpredictability; market demand for consumer devices utilizing semiconductors produced by our clients; our ability to manage costs; new product introductions, market acceptance of new products and enhanced versions of our existing products; reliability and technical acceptance of our products; our lengthy sales cycles, and the timing of system installations and acceptances; lengthy and costly development cycles for laser-processing and lithography technologies and applications; competition and consolidation in the markets we serve; improvements, including in cost and technical features, of competitors' products; rapid technological change; pricing pressures and product discounts; our ability to collect receivables; customer and product concentration and lack of product revenue diversification; inventory obsolescence; general economic, financial market and political conditions and other factors outside of our control; domestic and international tax policies; cybersecurity threats in the United States and globally that could impact our industry, customers, and technologies; and other factors described in our SEC reports including our Annual Report on Form 10K filed for the year ended December 31, 2015 and our Quarterly Report on Form 10-Q for the quarter ended October 1, 2016. Due to these and other factors, the statements, historical results and percentage relationships set forth herein are not necessarily indicative of the results of operations for any future period. We undertake no obligation to revise or update any forwardlooking statements to reflect any event or circumstance that may arise after the date of this release.

About Ultratech: Ultratech, Inc. (Nasdaq: UTEK) designs, builds and markets manufacturing systems for the global technology industry. Founded in 1979, Ultratech serves three core markets: frontend semiconductor, backend

semiconductor, and nanotechnology. The company is the leading supplier of lithography products for bump packaging of integrated circuits and high brightness LEDs. Ultratech is also the market leader and pioneer of laser spike anneal technology for the production of advanced semiconductor devices. In addition, the company offers solutions leveraging its proprietary coherent gradient sensing (CGS) technology to the semiconductor wafer inspection market and provides atomic layer deposition (ALD) tools to leading research organizations, including academic and industrial institutions. Visit Ultratech online at: www.ultratech.com.
(UTEKG)

Unity Platform is a trademark of Ultratech, Inc.

To view the original version on PR Newswire, visit:<http://www.prnewswire.com/news-releases/ultratech-receives-large-repeat-multiple-system-order-for-leading-edge-fan-out-wafer-level-packaging-applications-300408476.html>

SOURCE Ultratech, Inc.

News Provided by Acquire Media